

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Madan Krishnappa</td><td>02/04/2013</td></tr><tr><td>Stephen Simmonds</td><td>01/24/2013</td></tr><tr><td>Parag Arun Agashe</td><td>01/24/2013</td></tr><tr><td>Sajjad Pagarkar</td><td>02/05/2013</td></tr><tr><td>Ashwin Rabindranath</td><td>01/26/2013</td></tr><tr><td>Sagar Digwalekar</td><td>02/06/2013</td></tr></tbody></table>		Name	Execution Date	Madan Krishnappa	02/04/2013	Stephen Simmonds	01/24/2013	Parag Arun Agashe	01/24/2013	Sajjad Pagarkar	02/05/2013	Ashwin Rabindranath	01/26/2013	Sagar Digwalekar	02/06/2013
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RECEIVING PARTY DATA															
<table border="1"><tr><td>Name:</td><td>QUALCOMM Incorporated</td></tr><tr><td>Street Address:</td><td>5775 Morehouse Drive</td></tr><tr><td>City:</td><td>San Diego</td></tr><tr><td>State/Country:</td><td>CALIFORNIA</td></tr><tr><td>Postal Code:</td><td>92121</td></tr></table>		Name:	QUALCOMM Incorporated	Street Address:	5775 Morehouse Drive	City:	San Diego	State/Country:	CALIFORNIA	Postal Code:	92121				
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PROPERTY NUMBERS Total: 1															
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13736295</td></tr></tbody></table>		Property Type	Number	Application Number:	13736295										
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Application Number:	13736295														
CORRESPONDENCE DATA															
Fax Number: 8586582502 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
Email: us-docketing@qualcomm.com															
Correspondent Name: QUALCOMM Incorporated															
Address Line 1: 5775 Morehouse Drive															
Address Line 4: San Diego, CALIFORNIA 92121															
ATTORNEY DOCKET NUMBER:	120629														
NAME OF SUBMITTER:	Daniel Rodrigues														

CH \$40.00 13736295

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PATENT
REEL: 029955 FRAME: 0414

Total Attachments: 18

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source=120629_2013-02-06_Signed_Assignment#page2.tif
source=120629_2013-02-06_Signed_Assignment#page3.tif
source=120629_2013-02-06_Signed_Assignment#page4.tif
source=120629_2013-02-06_Signed_Assignment#page5.tif
source=120629_2013-02-06_Signed_Assignment#page6.tif
source=120629_2013-02-06_Signed_Assignment#page7.tif
source=120629_2013-02-06_Signed_Assignment#page8.tif
source=120629_2013-02-06_Signed_Assignment#page9.tif
source=120629_2013-02-06_Signed_Assignment#page10.tif
source=120629_2013-02-06_Signed_Assignment#page11.tif
source=120629_2013-02-06_Signed_Assignment#page12.tif
source=120629_2013-02-06_Signed_Assignment#page13.tif
source=120629_2013-02-06_Signed_Assignment#page14.tif
source=120629_2013-02-06_Signed_Assignment#page15.tif
source=120629_2013-02-06_Signed_Assignment#page16.tif
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ASSIGNMENT

WHEREAS, WE,

1. Madan Krishnappa, a citizen of India, having a mailing address located at having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, CA,
2. Stephen Simmonds, a citizen of United States of America, having a mailing address located at having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, CA,
3. Parag Arun Agashe, a citizen of United States of America, having a mailing address located at having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, CA,
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have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **METHOD FOR PERFORMING ADAPTIVE VOLTAGE SCALING (AVS) AND INTEGRATED CIRCUIT CONFIGURED TO PERFORM AVS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/736,295, filed January 08, 2013, Qualcomm Reference No. 120629, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Pondicherry, on 02/04/2013 Madan Krishnappa
LOCATION DATE

Done at _____, on _____
LOCATION DATE Stephen Simmonds

Done at _____, on _____
LOCATION DATE Parag Arun Agashe

Done at _____, on _____
LOCATION DATE Sajjad Pagarkar

Done at _____, on _____
LOCATION DATE Ashwin Rabinathanath

Done at _____, on _____
LOCATION DATE Sagar Digwalekar

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its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/736,295, filed January 08, 2013, Qualcomm Reference No. 120629, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

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AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

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all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Madan Krishnappa

Done at San Diego, on Jan 24, 2013
LOCATION DATE Stephen Simmonds

Done at _____, on _____
LOCATION DATE Parag Arun Agashe

Done at _____, on _____
LOCATION DATE Sajjad Pagarkar

Done at _____, on _____
LOCATION DATE Ashwin Rabindranath

Done at _____, on _____
LOCATION DATE Sagar Digwalekar

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WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s), 13/736,295, filed January 08, 2013, Qualcomm Reference No. 120629, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

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AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

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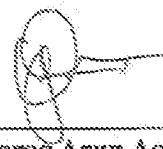
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AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Madan Krishnappa

Done at _____, on _____
LOCATION DATE Stephen Simmonds

Done at San Diego, CA, on 01-24-2013
LOCATION DATE 
Parag Arun Agashe

Done at _____, on _____
LOCATION DATE Sajjad Pagarkar

Done at _____, on _____
LOCATION DATE Ashwin Rabindranath

Done at _____, on _____
LOCATION DATE Sagar Digwalekar

ASSIGNMENT

WHEREAS, WE,

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Done at _____, on _____
LOCATION DATE Madan Krishnappa

Done at _____, on _____
LOCATION DATE Stephen Simmonds

Done at _____, on _____
LOCATION DATE Parag Arun Agashe

Done at SAN DIEGO, on 02/05/2013
LOCATION DATE Sajjad Pagarkar

Done at _____, on _____
LOCATION DATE Ashwin Rabindranath

Done at _____, on _____
LOCATION DATE Sagar Digwalekar

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WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **13/736,295**, filed **January 08, 2013**, Qualcomm Reference No. **120629**, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Madan Krishnappa

Done at _____, on _____
LOCATION DATE Stephen Simmonds

Done at _____, on _____
LOCATION DATE Parag Arun Agashe

Done at _____, on _____
LOCATION DATE Sajjad Pagarkar

Done at SAN DIEGO, on 1/26/2013
LOCATION DATE Ashwin Rabiadrath

Done at _____, on _____
LOCATION DATE Sagar Digwalekar

ASSIGNMENT

WHEREAS, WE,

1. Madan Krishnappa, a citizen of India, having a mailing address located at having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, CA,
2. Stephen Simmonds, a citizen of United States of America, having a mailing address located at having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, CA,
3. Parag Arun Agashe, a citizen of United States of America, having a mailing address located at having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, CA,
4. Sajjad Pagarkar, a citizen of India, having a mailing address located at having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, CA,
5. Ashwin Rabindranath, a citizen of India, having a mailing address located at having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, CA,
6. Sagar Digwalekar, a citizen of India, having a mailing address located at having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, CA,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **METHOD FOR PERFORMING ADAPTIVE VOLTAGE SCALING (AVS) AND INTEGRATED CIRCUIT CONFIGURED TO PERFORM AVS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). **13/736,295**, filed **January 08, 2013**, Qualcomm Reference No. **120629**, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Madan Krishnappa

Done at _____, on _____
LOCATION DATE Stephen Simmonds

Done at _____, on _____
LOCATION DATE Parag Arun Agashe

Done at _____, on _____
LOCATION DATE Sajjad Pagarkar

Done at _____, on _____
LOCATION DATE Ashwin Rabindrunath

Done at San Diego, CA, on 2/6/2013
LOCATION DATE Sagar Digwalekar